## Declaration and Power of Attorney for Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address first and sole inventor (if only one listed below) of the subject matter	name is listed below) or	an original, first and jo	int inventor (if plural names are
FLIP CHIP PACKAGE	WITH HEAT SPREAD ATTACHI		TIPLE HEAT SINK
the specification of which (check o		,22,2 1 2	
is attach	ed hereto.	·	
was filed	d on as Applica	tion Serial No.	and was amended on
<u> </u>			
I hereby state that I have reviewed claims, as amended by any amenda		ents of the above- identi	fied specification, including the
I acknowledge the duty to disclose with Title 37, Code of Federal Regi		erial to the patentability	of this application in accordance
I hereby claim foreign priority ben patent or inventor's certificate list inventor's certificate having a filing	ed below and have also	identified below any fo	oreign application for patent or
Prior Foreign Application	(s):		
Number Country N/A		ar Priority Claimed	
I hereby claim the benefit under Ti and, insofar as the subject matter o application in the manner provided duty to disclose information materi Regulations, §1.56 which occurre international filing date of this appl	f each of the claims of the by the first paragraph of all to the patentability of d between the filing da	is application is not disc Title 35, United States this application as defin	closed in the prior United States Code, §112, I acknowledge the led in Title 37, Code of Federal
Prior U.S. Applications:			
Serial No.	Filing Date	Status	
I hereby declare that all statement information and belief are believed	s made herein of my ow to be true; and further the	m knowledge are true a nat these statements were	nd that all statements made on e made with the knowledge that

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

As a named inventor, I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: David L. Adour, Registration No. 29,604; John R. Pivnichny, Registration No. 43,001; Arthur J. Samodovitz, Registration No. 31,297; William H. Steinberg, Registration No. 28,540; William E. Schiesser, Registration No. 53,559; JoAnn K. Crockatt, Registration No. 36,493; Joseph Petrokaitis, Registration No. 38,995; all of INTERNATIONAL BUSINESS MACHINES CORPORATION; and John E. Hoel, Registration No. 26,279; Christopher A. Hughes, Registration No. 26,914; Joseph C. Redmond, Jr., Registration No. 18,753; all of MORGAN & FINNEGAN, L.L.P. and John A. Jordan, Registration No. 24,655.

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